

60V N-Channel DTMOS

Features

- Trench Power DTMOS Technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for Fast-switching Applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

Product Summary

V_{DS} 60V

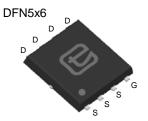
RDS(ON) (at VGS=10V) $< 15m\Omega$

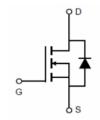
RDS(ON) (at VGS=4.5V) $< 19m\Omega$

ID (at VGS=10V) 45A

100% UIS Tested







Device	Package	Marking
TSG10N06AT	DFN5×6	10N06AT

Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted				
Parameter		Symbol	Value	Unit
Drain-Source Voltage (V _{GS} =	0V)	V _{DSS}	60	V
Continuous Proin Current	$T_{\rm C} = 25^{\rm 0}{\rm C}$	l _D	45	· A
Continuous Drain Current	$T_{\rm C} = 100^{\rm o}{\rm C}$		27	
Pulsed Drain Current	(note1)	I _{DM}	180	А
Gate-Source Voltage		V_{GSS}	±20	V
Single Pulse Avalanche Ene	rgy (note2)	E _{AS}	20	mJ
Avalanche Current	(note1)	I _{As}	20	Α
Power Dissipation ($T_C = 25^{\circ}C$)		P_{D}	56.5	W
Operating Junction and Stora	age Temperature Range	T_J , T_{stg}	-55~+175	°C

Thermal Resistance				
Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	R _{thJC}	2.1	0000	
Thermal Resistance, Junction-to-Ambient	R_{thJA}	50	°C/W	



			Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	- Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60			V	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μΑ	
		$V_{DS} = 60V, V_{GS} = 0V, T_{J} = 100^{\circ}C$			100		
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1		2.5	V	
Dunin Course On Benistance (Nets2)	Б	$V_{GS} = 10V, I_D = 20A$		12	15	0	
Drain-Source On-Resistance (Note3)	$R_{DS(on)}$	$V_{GS} = 4.5V, I_{D} = 18A$		15	19	mΩ	
Forward Transconductance (Note3)	g _{fs}	$V_{DS} = 5V, I_{D} = 20A$		100		S	
Dynamic							
Input Capacitance	C _{iss}	V - 0V		1134		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 30V,$		123			
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		12			
Total Oats Obanna	Q _g (10V)	$V_{DD} = 30V, I_{D} = 20A,$		21		nC	
Total Gate Charge	Q _g (4.5V)			11			
Gate-Source Charge	Q_{gs}	$V_{GS} = 10V$		3.1			
Gate-Drain Charge	Q_{gd}			5.1			
Turn-on Delay Time	t _{d(on)}			7			
Turn-on Rise Time	t _r	$V_{DD} = 30V, I_{D} = 20A,$		3			
Turn-off Delay Time	t _{d(off)}	$R_G = 3\Omega$		20		ns	
Turn-off Fall Time	t _f			3			
Drain-Source Body Diode Characteris	stics						
Continuous Body Diode Current	I _S	T 0500			30	Λ.	
Pulsed Diode Forward Current	I _{SM}	$T_C = 25^{\circ}C$			90	A	
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}\text{C}, I_{SD} = 1\text{A}, V_{GS} = 0\text{V}$		0.72	1	V	
Reverse Recovery Time	t _{rr}	I _F = 20A,		17		ns	
Reverse Recovery Charge	Q _{rr}	$di_F/dt = 500A/\mu s$		60		nC	

Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. I_{AS} = 20A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 1%

Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

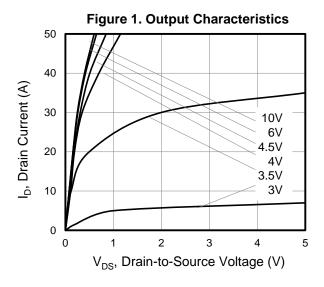


Figure 3. On-Resistance vs. Drain Current

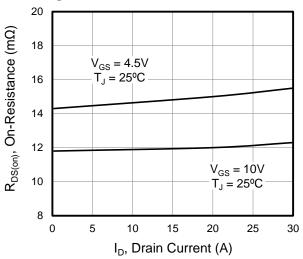


Figure 5. Gate Charge

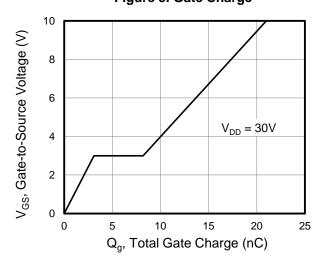


Figure 2. Transfer Characteristics

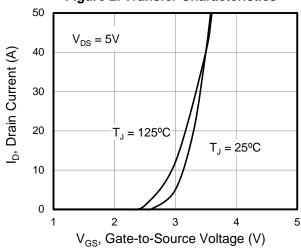


Figure 4. Capacitance

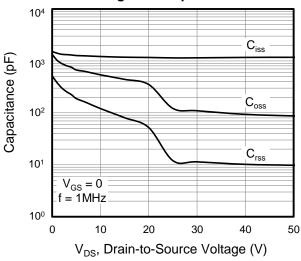
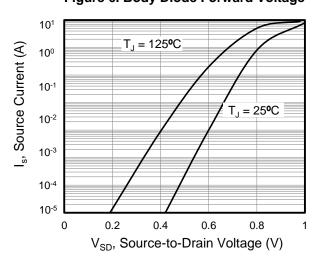


Figure 6. Body Diode Forward Voltage



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

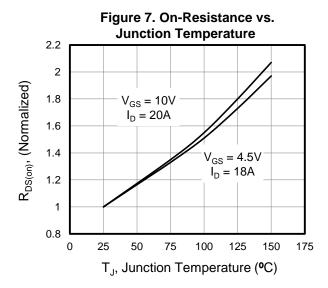


Figure 9. Transient Thermal Impedance

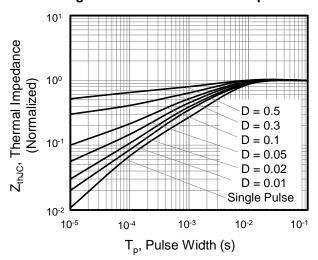


Figure 8. Threshold Voltage vs. Junction Temperature 1.2 1.1 V_{GS(th)}, (Variance) $I_{D} = 250 \mu A$ 0.9 8.0 0.7 0.6 -100 -50 0 50 100 150 200 T_J, Junction Temperature (°C)

Figure 10. Safe operation area

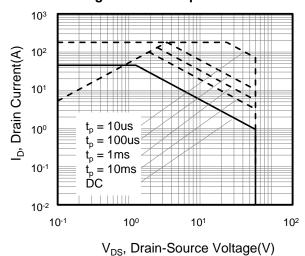




Figure A: Gate Charge Test Circuit and Waveform

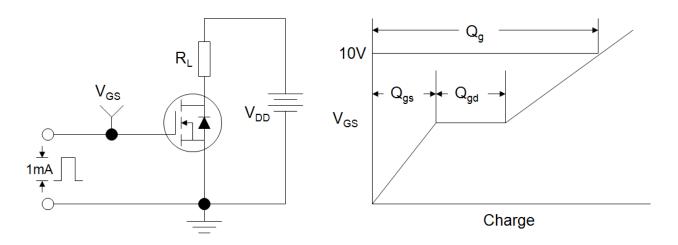


Figure B: Resistive Switching Test Circuit and Waveform

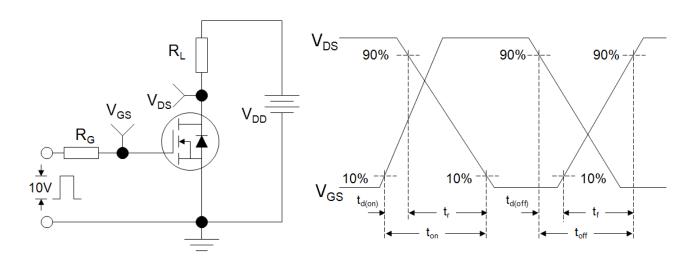
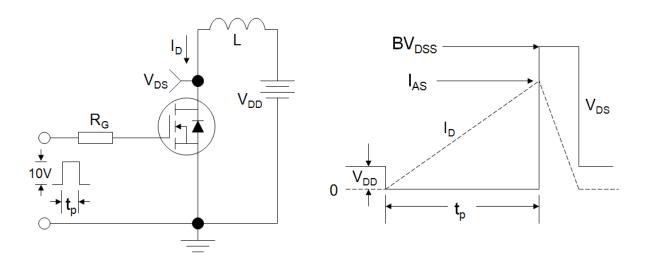
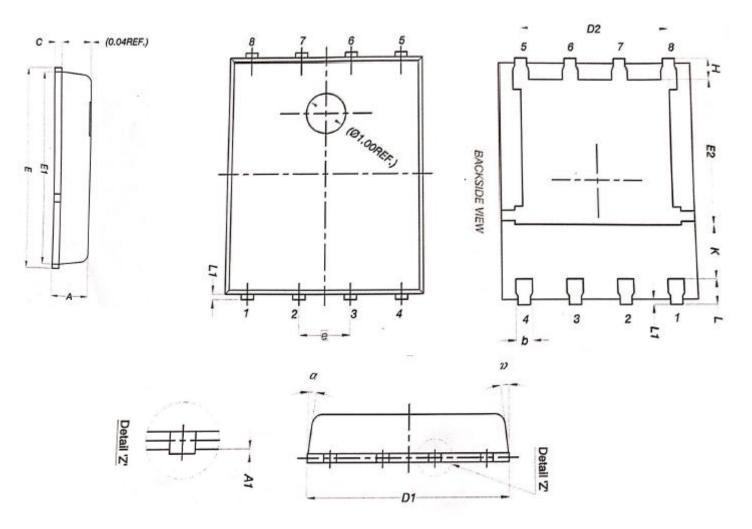


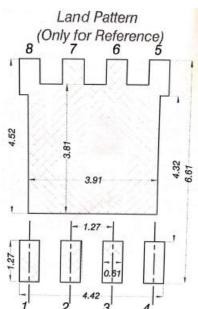
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



DFN5×6 PACKAGR OUTLINE



544	MILLIMETERS			
DIM.	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	
A1	0	ı	0.05	
b	0.33	0.41	0.51	
С	0.20	0.25	0.30	
D1	4.80	4.90	5.00	
D2	3.61	3.81	3.96	
E	5.90	6.00	6.10	
E1	5.70	5.75	5.80	
E2	3.38	3.58	3.78	
е	1.27 BSC			
Н	0.41	0.51	0.61	
K	1.10	-	-	
L	0.51	0.61	0.71	
L1	0.06	0.13	0.20	
a.	O°		12°	





Disclaimer

All product specifications and data are subject to change without notice.

For documents and material available from this datasheet, Wuxi Unigroup does not warrant or assume any legal liability or responsibility for the accuracy, completeness of any product or technology disclosed hereunder.

No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document or by any conduct of Wuxi Unigroup.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling Wuxi Unigroup products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Wuxi Unigroup for any damages arising or resulting from such use or sale.

Wuxi Unigroup disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Wuxi Unigroup's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

Wuxi Unigroup Microelectronics CO., LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all Wuxi Unigroup products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

Information (including circuit diagrams and circuit parameters) herein is for example only. It is not guaranteed for volume production. Wuxi Unigroup believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by UNIGROUP manufacturer:

Other Similar products are found below:

614233C 648584F MCH3443-TL-E MCH6422-TL-E FDPF9N50NZ FW216A-TL-2W FW231A-TL-E APT5010JVR NTNS3A92PZT5G IRF100S201 JANTX2N5237 2SK2464-TL-E 2SK3818-DL-E FCA20N60_F109 FDZ595PZ STD6600NT4G FSS804-TL-E 2SJ277-DL-E 2SK1691-DL-E 2SK2545(Q,T) D2294UK 405094E 423220D MCH6646-TL-E TPCC8103,L1Q(CM 367-8430-0972-503 VN1206L 424134F 026935X 051075F SBVS138LT1G 614234A 715780A NTNS3166NZT5G 751625C 873612G IRF7380TRHR IPS70R2K0CEAKMA1 RJK60S3DPP-E0#T2 RJK60S5DPK-M0#T0 APT5010JVFR APT12031JFLL APT12040JVR DMN3404LQ-7 NTE6400 JANTX2N6796U JANTX2N6784U JANTXV2N5416U4 SQM110N05-06L-GE3 SIHF35N60E-GE3